



## Thermal performance of a novel porous crack composite wick heat pipe



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### ABSTRACT

A novel porous crack composite wick flattened heat pipe (PCHP) has been developed for electronic device cooling. PCHP was fabricated from grooved-sintered wick cylindrical heat pipe (GSHP) by phase change flattening technology. The composite wick was composed of porous sintered powder structure and axial micro-crack channels. The crack channels of composite wick were characterized and the calculation models of thermal resistance and capillary limit of PCHP were built. An experimental setup was used to test thermal resistance and heat transfer limit. The results showed that the parameters affecting thermal resistance from the most significant to the least one were wick thickness, powder diameter, flattened height, and tear number. The optimal wick thickness of PCHP for the maximum heat transfer limit was about 0.45 mm at flattened height of 3 mm. Heat transfer limit of PCHP increased with powder diameter while decrease of powder diameter could enhance anti-gravity ability of PCHP. Heat transfer limit of PCHP increased with flattened height. The effect of tear number on thermal resistance and heat transfer limit of PCHP could be neglected.

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### 1. Introduction

High performance electronics requires heat transfer devices with high heat conductivity, quick thermal response speed, small size and high reliability to dissipate heat [1–3]. The heat pipe has received increased attention due to its excellent thermal performance [4]. The thermal performance of heat pipe for high power electronics cooling is usually governed by their wick structure [2,5]. The wick structure provides the capillary pressure and flow path to drive working liquid transferring from evaporation section to condensation section of heat pipe. However, it is difficult for homogeneous wick to satisfy two contrasting demands such as large capillary ability and high liquid permeability [6]. The grooved wick has high liquid permeability, yet limited capillary ability while the properties of sintered wick are in reverse [1,2,7]. Therefore, composite wicks have been developed to balance the contradictions between high capillary ability and high permeability.

Many researches have shown that thermal performance of composite wick heat pipe was usually higher than that of monoporous wick, such as biporous wick, modulated wick, powder-mesh com-

posite wick and sintered-grooved composite wick. Semenic et al. [8,9] fabricated biporous wicks with two characteristic pore sizes by sintering clusters of powder together. Biporous wicks improved performance through increased capillary pressure and permeability. Wang and Catton [10] investigated a composite wick with a thin porous layer on the triangular grooves. Modeling analysis results showed it could improve capillary force and extend evaporation surface. Hwang et al. [11] fabricated modulated wick which was comprised of periodic stacks and grooves over a thin and uniform wick. The wick provided extra cross-sectional area to enhance axial capillary liquid flow and extend extra evaporation surface area with a moderate increase in conduction resistance of wick. Franchi [7] fabricated a composite wick by solid state sintering fine metal powder onto the layers of coarse pore copper mesh. The wick structure enhanced evaporation heat transfer at the liquid/vapor interface and the extension of the capillary limit. Tang et al. [12–14] and Li et al. [15] fabricated sintered-grooved wick by sintering copper powder in or over grooves. Experimental results showed that composite wicks enhanced both the permeability and capillary force compared to sintered wicks, and exhibited much larger capillary pressure than grooved wick. Above all, thermal performance of optimized composite wick can be enhanced by increase or balance of capillary pressure or permeability.

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